

Claims

1. Reamer comprising a base body with a cutting element and at least one guiding strip aligned essentially axially with an abutment surface and a guiding surface, whereby the guiding surface is connected to the base body in the area of the abutment surface, characterized in that the guiding strip is formed of layered bodies of different materials running from the guiding surface to the abutment surface.
2. Reamer according to claim 1, characterized in that the layered bodies run essentially parallel to the rotational axis of the base body.
3. Reamer according to claim 1 or 2, characterized in that the layered bodies run essentially perpendicular to the rotational direction of the base body.
4. Reamer according to one of claims 1 through 3, characterized in that the guiding strip has layered bodies of hard metal and layered bodies of diamond or cubic boron nitride.
5. Reamer according to one of claims 1 through 4, characterized in that the guiding strip comprises layered bodies of hard metal with a thickness of 1000 μm to 1500 μm .
6. Reamer according to one of claims 1 through 5, characterized in that the guiding strip comprises layered bodies of diamond or cubic boron nitride with a thickness of 2 μm to 500 μm , in particular 10 μm to 50 μm .
7. Reamer according to one of claims 1 through 6, characterized in that at least one layered body is made of hard metal and is connected to a layered body of diamond.
8. Reamer according to claim 7, characterized in that the layered body of diamond is made through deposition of diamond on the layered body of hard metal.
9. Reamer according to claim 7 or 8, characterized in that the guiding strip has layered bodies of diamond which are connected with a first solder mass.

10. Reamer according to claim 9, characterized in that the first solder mass contains copper and silver as main constituents and titanium and/or yttrium as further elements.
11. Reamer according to claim 9 or 10, characterized in that the layered body/bodies formed through the first solder mass has/have a thickness of 10 μm to 25 μm .
12. Reamer according to one of claims 9 through 11, characterized in that the guiding strip is connected to the base body by a second solder mass which has a lower melting point than a first solder mass.
13. Reamer according to one of claims 1 through 11, characterized in that the guiding strip is connected to the base body by an adhesive mass.